



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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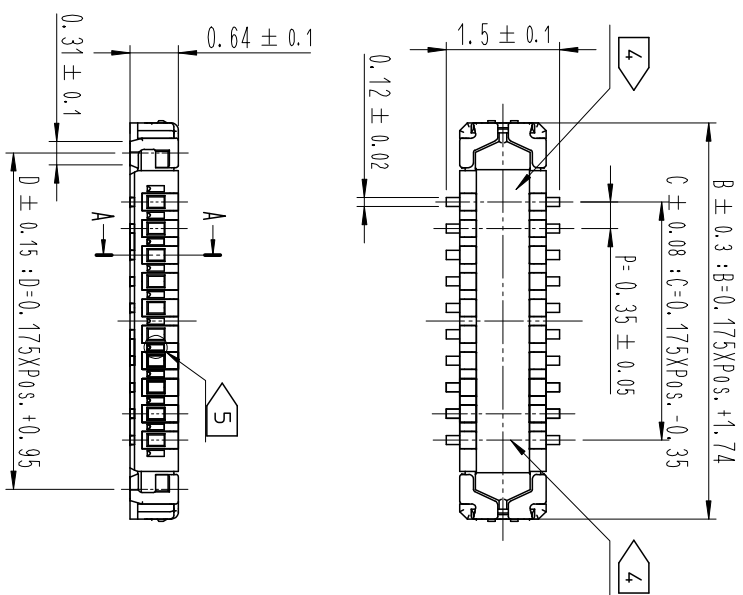
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



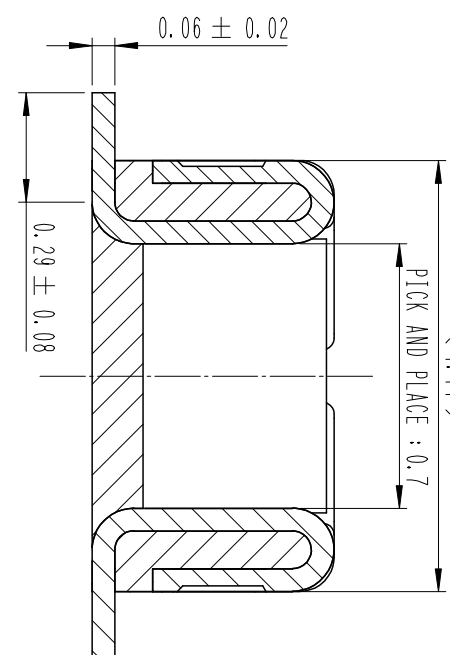
DRAWING FOR REFERENCE
 This is subject to change without notice

COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
2	RE-6-0742			LYJ	16.09.27						
3	RE-6-0806			MSH	17.01.05						

△ PART No.	CODE No.	POS.	B	C	D
BM23PF0.8-10DP-0.35V(51)	-	10	3.49	1.40	2.70
BM23PF0.8-14DP-0.35V(51)	-	14	4.19	2.10	3.40
BM23PF0.8-20DP-0.35V(51)	-	20	5.24	3.15	4.45
BM23PF0.8-24DP-0.35V(51)	-	24	5.94	3.85	5.15
BM23PF0.8-40DP-0.35V(51)	-	40	8.74	6.65	7.95
BM23PF0.8-42DP-0.35V(51)	-	42	9.09	7.00	8.30
BM23PF0.8-46DP-0.35V(51)	-	46	9.79	7.70	9.00
BM23PF0.8-54DP-0.35V(51)	-	54	11.19	9.10	10.40



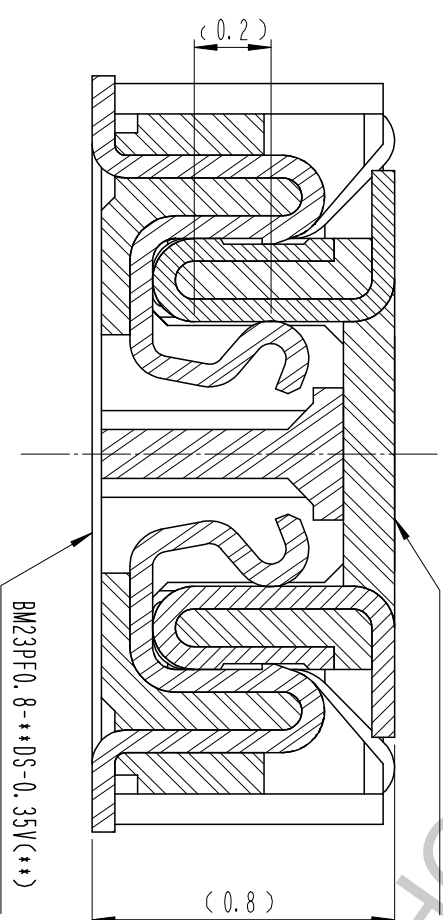
A:A(50:1)



NOTE
 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.

- 2. CONTACT PLATING SPECIFICATIONS.
 CONTACT AREA : GOLD 0.05µm MIN.
 SMT LEAD : GOLD 0.05µm MIN.
 UNDER PLATING : NICKEL 1µm MIN.
 (SURFACE : SEALING)
- 3. METAL FITTING PLATING SPECIFICATIONS.
 SMT LEAD : GOLD 0.05µm MIN.
 UNDERPLATING : NICKEL 1µm MIN.
 (SURFACE : SEALING)
- 4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
- 5. A PART OF THE WALL COULD BE NOTCHED.

ENGAGEMENT FIGURE (50:1)



HRS DRAWING FOR REFERENCE

NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
2	COOPER ALLOY		6	PS	BLACK (PLASTIC REEL)
3	COOPER ALLOY		7	PS	CLEAR (REINFORCEMENT COLLAR)
4	PS	CLEAR (EMBOSSED CARRIER TAPE)			

REMARKS

CODE NO. (OLD)	SCALE	DRAWING NO.	PART NO.	CODE NO
	10:1	EDC3-*****	BM23PF0.8-42DP-0.35V(51)	CL 66*****

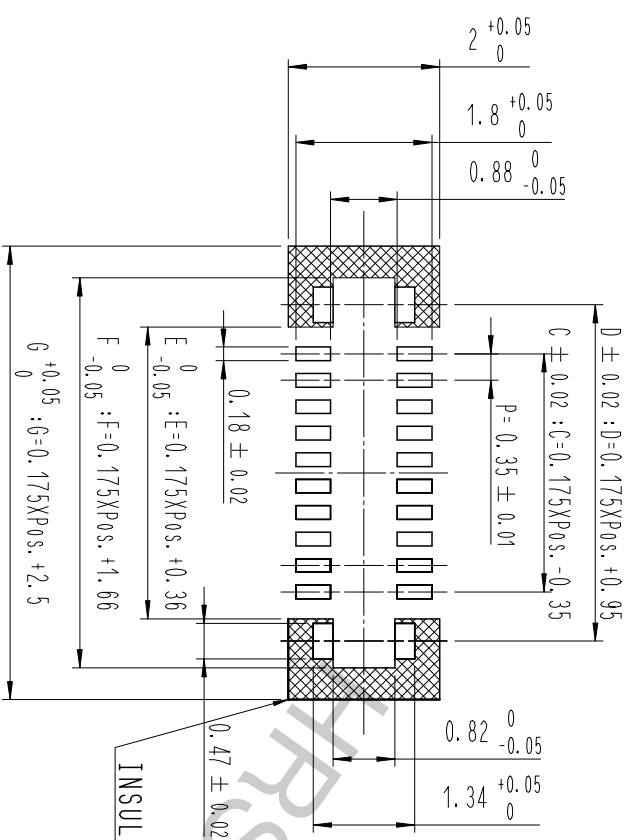
SCALE	DRAWING NO.	PART NO.	CODE NO
10:1	EDC3-*****	BM23PF0.8-42DP-0.35V(51)	CL 66*****

HRS HIROSE KOREA CO., LTD.

CL 66*****

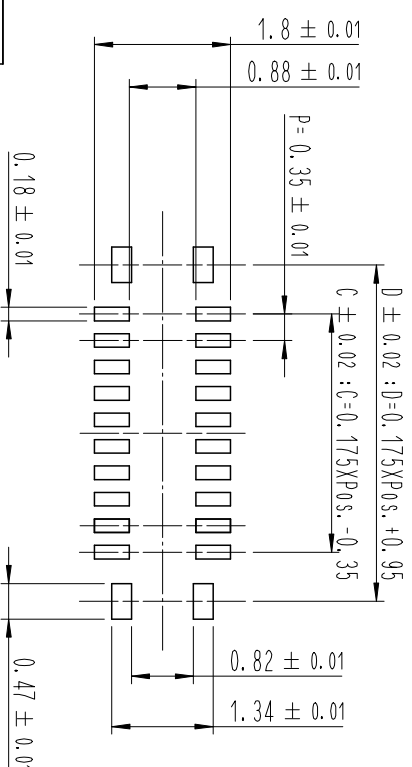
1/3

7 RECOMMENDED PCB LAYOUT

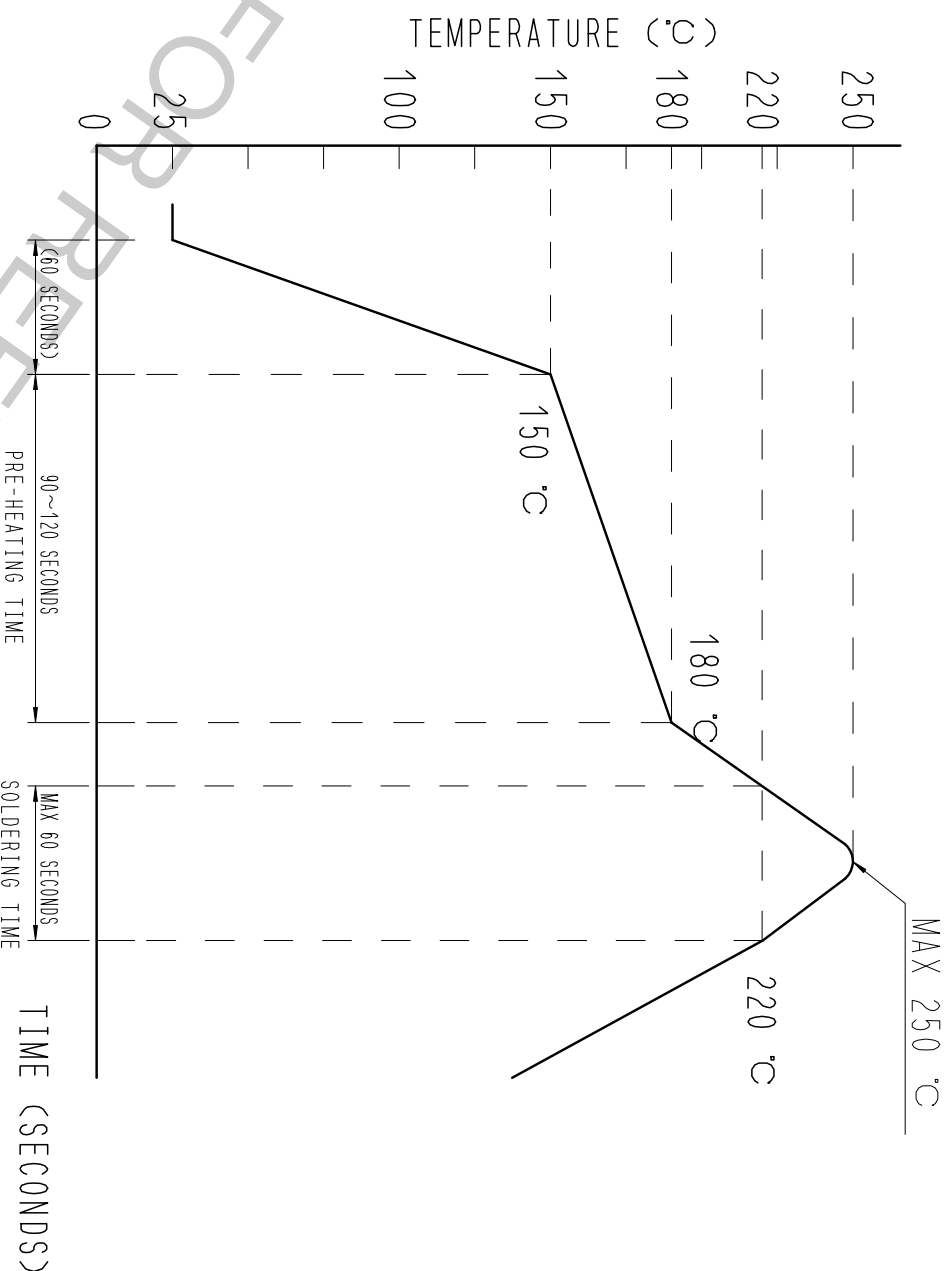


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
 1) REFLOW TIME
 DURATION ABOVE 220°C: 60 SEC MAX.
 (PEAK TEMPERATURE: 250°C MAX)
 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE (MIN): 150°C
 PRE-HEAT TEMPERATURE (MAX): 180°C
 PRE-HEAT TIME: 90-120 SEC.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
 ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
 OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
 A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
 PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

POS.	C	D	E	F	G
10	1.40	2.70	2.11	3.41	4.25
14	2.10	3.40	2.81	4.11	4.95
20	3.15	4.45	3.86	5.16	6.00
24	3.85	5.15	4.56	5.86	6.70
40	6.65	7.95	7.36	8.66	9.50
42	7.00	8.30	7.71	9.01	9.85
46	7.70	9.00	8.41	9.71	10.55
54	9.45	10.75	10.16	11.46	12.30

DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-**-DP-0.35V(51)
SCALE	10:1	CODE NO	CL 66*-**-***
UNITS	mm		

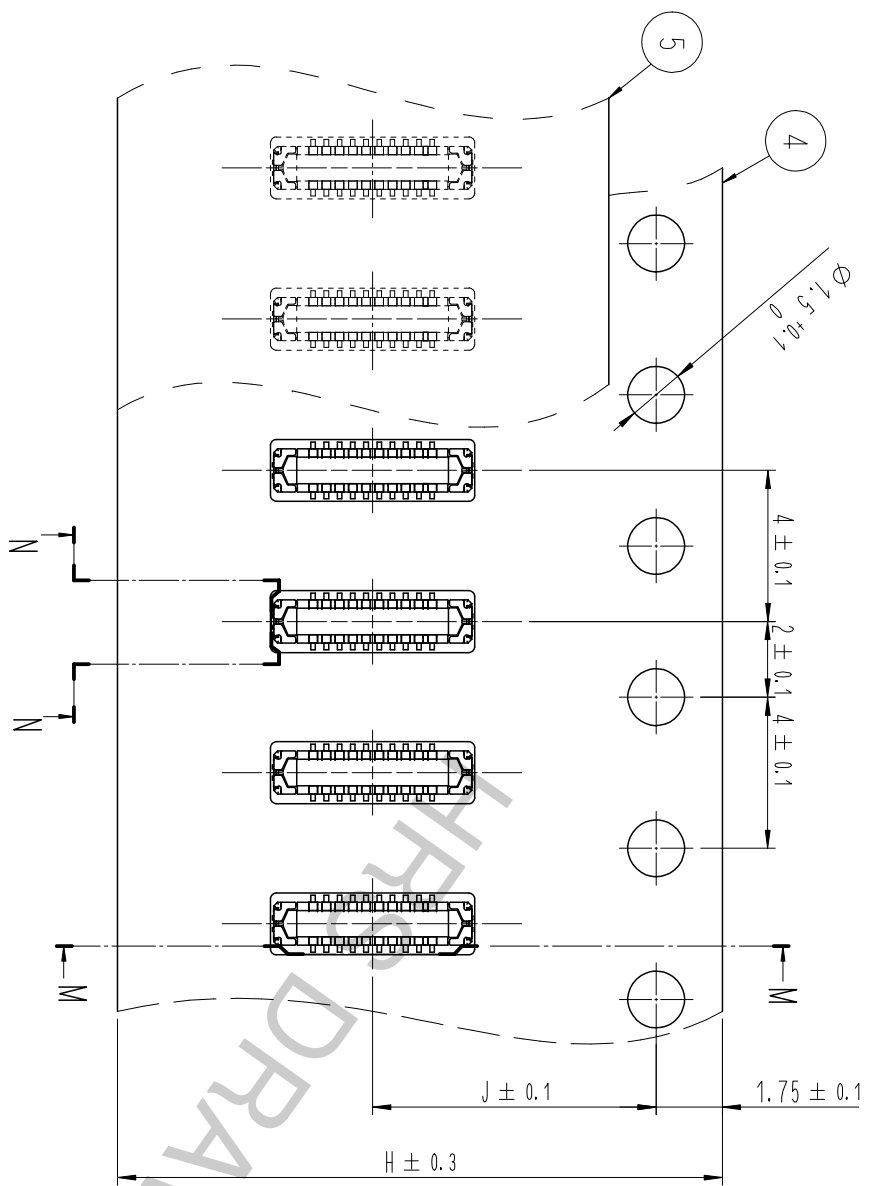
HRS HIROSE KOREA CO., LTD.

CL 66*-**-***

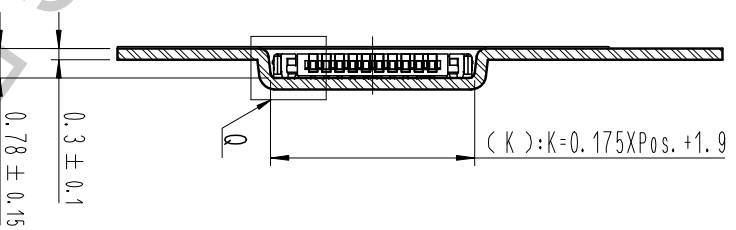
2

3

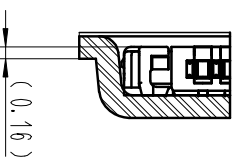
EMBOSSED CARRIER TAPE PACKAGING (5:1)



M-M (5:1)

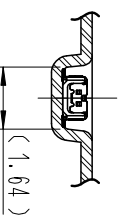


Q (10:1)

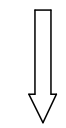


POS.	H	J	K	L	M
10	12	5.5	3.65	13.5	17.5
14	16	7.5	4.35	17.5	21.5
20	16	7.5	5.40	17.5	21.5
24	16	7.5	6.10	17.5	21.5
40	24	11.5	8.90	25.5	29.5
42	24	11.5	9.25	25.5	29.5
46	24	11.5	9.95	25.5	29.5
54	24	11.5	11.35	25.5	29.5

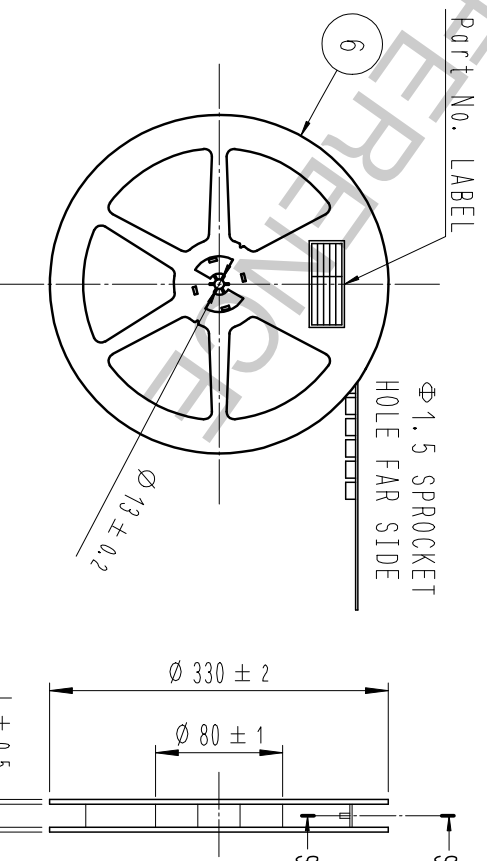
N-N (5:1)



DIRECTION OF UNREELING



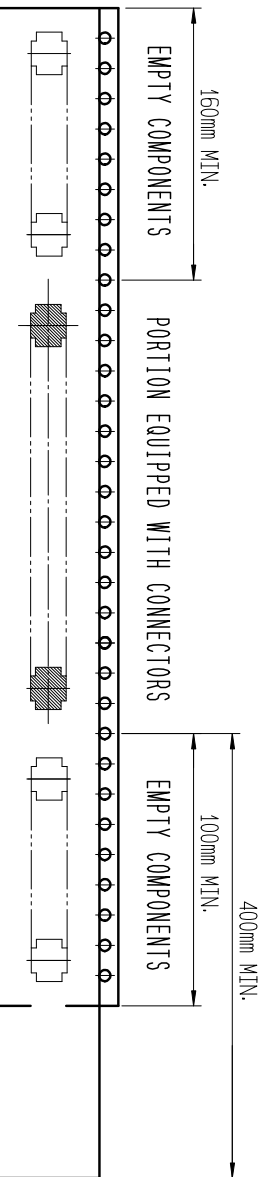
STYLE AND DIMENTION OF REEL (FREE)



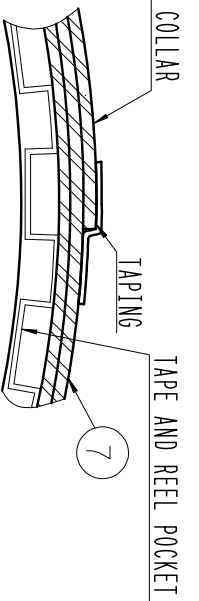
DETAIL OF PART NO. LABEL

SUPPLIER	年 月 日
QUANTITY	** ** *
PART NO.	品名
CODE NO.	BM23PF0.8-**-DP-0.35V(51)
DATE OF MANUFACTURED	納入数量
	10,000個
	納入者
	HIROSE KOREA

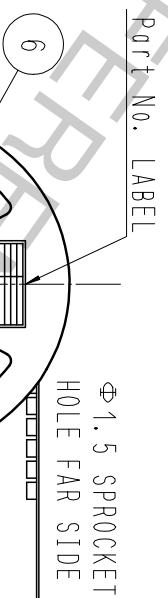
10 TAPING(FREE)



11 REINFORCEMENT COLLAR



Part No. LABEL



8 . PER REEL 10,000 CONNECTORS.

9 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

10 REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING) AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-**-DP-0.35V(51)
SCALE	10:1	CODE NO	CL 66***-***-***
UNITS	mm		

TRAILER

LEADER

HRS HIROSE KOREA CO., LTD.

CODE NO

CL 66***-***-***

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